

## XP-002088741

1/1 - (C) WPI / DERWENT  
AN - 84-149562 ç24!  
AP - JP820189496 821028  
PR - JP820189496 821028  
TI - Synthetic resin thin film prodn. - by forming substrate film then top film, and dissolving substrate with non-solvent for top film  
IW - SYNTHETIC RESIN THIN FILM PRODUCE FORMING SUBSTRATE FILM TOP FILM DISSOLVE SUBSTRATE NON SOLVENT TOP FILM  
PA - (SHOX ) SHOWA ELECTRIC WIRE CO LTD  
PN - JP59078816 A 840507 DW8424 003pp  
ORD - 1984-05-07  
IC - B29D7/00  
FS - CPI  
DC - A32  
AB - J59078816 Synthetic resin films are prepd. by forming a synthetic resin film on a substrate directly, then forming another synthetic resin film on this, and dripping the whole in a solvent, which dissolves and removes the resin constituting the underlying film but not the resin of the upper layer. Extremely thin films of synthetic resin can be prepd. easily without use of mercury which pollutes the environment.  
- Any material stable under film forming conditions and insoluble to the solvent used can be employed for substrates. Resins used for forming underlying films (and their solvents) are as follows: silicone resin (cresol, xylene, N-methyl-2-pyrrolidone), polyamide resin (ethyl alcohol, cresol), polyester resin (benzene, THF), polyvinyl alcohol resin (water). Resins used for forming upper layer films are polyamide, polyamideimide, polyester imide, polyester or polyurethane resins.(0/0)